DAILY SCHEDULE OF EVENTS

SUNDAY

EVENT	TIMES	LOCATION
Registration	5:00 pm – 8:00 pm	Presidential Foyer, Second Level
Welcome Reception	6:00 pm – 7:30 pm	Palm Court, Lobby Level

MONDAY

EVENT	TIMES	LOCATION
Registration	8:00 am – 6:00 pm	Presidential Foyer, Second Level
MO1: Opening Session	9:00 am – 9:30 am	Presidential Ballroom, Second Level, Salons C&D
MO2: Implant Systems	9:30 am -10:30 am	Presidential Ballroom, Second Level, Salons C&D
Exhibit	10:00 am – 5:00 pm	Presidential Ballroom, Second Level, Salons A&B
Break	10:30 am – 11:00 am	Presidential Ballroom, Second Level, Salons A&B
MO3: Plenary Session I	11:00 am -12:20 pm	Presidential Ballroom, Second Level, Salons C&D
Lunch	12:20 pm – 2:00 pm	Bivouac Ballroom, Historic Lower Level
MO4: Novel Doping Processes and Techniques	2:00 pm – 3:50 pm	Presidential Ballroom, Second Level, Salons C&D
Break	3:50 pm – 4:20 pm	Presidential Ballroom, Second Level, Salons A&B
MO5: Novel Annealing Processes and Techniques	4:20 pm – 5:50 pm	Presidential Ballroom, Second Level, Salons C&D

TUESDAY

EVENT	TIMES	LOCATION
Registration	8:00 am – 6:00 pm	Presidential Foyer, Second Level
TU1: Doping Applications	9:00 am – 10:40 am	Presidential Ballroom, Second Level, Salons C&D
Exhibit	10:00 am - 5:30 pm	Presidential Ballroom, Second Level, Salons A&B
Break	10:40 am – 11:10 am	Presidential Ballroom, Second Level, Salons A&B
TU2: Advanced Implant/Doping and Annealing Equipment	11:10 am –12:50 pm	Presidential Ballroom, Second Level, Salons C&D
Lunch	12:50 pm - 2:00 pm	Bivouac Ballroom, Historic Lower Level
TU3: Annealing Technologies and Processes I	2:00 pm – 3:50 pm	Presidential Ballroom, Second Level, Salons C&D
TU4: Plenary Session II	3:50 pm - 4:30 pm	Presidential Ballroom, Second Level, Salons C&D
PS1: Poster Session I	4:30 pm – 5:30 pm	Presidential Ballroom, Second Level, Salon A&B & Foyer

Join us for the CONFERENCE BANQUET

Wednesday, 7:30 pm – 10:00 pm Bivouac Ballroom Don't miss this year's Conference Dinner Banquet, Wednesday evening in the Bivouac Ballroom located on the Historic Lower Level of the US Grant. Full Conference registration includes one Dinner admission. You can purchase additional Dinner tickets at the IIT Registration Desk for \$155 USD, subject to availability.

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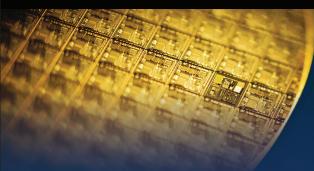
WEDNESDAY

EVENT	TIMES	LOCATION
Registration	8:00 am – 2:00 pm	Presidential Foyer, Second Level
WE1: Advanced Metrologies for Implant/Doping and Annealing Processes I	9:00 am – 10:10 am	Presidential Ballroom, Second Level, Salons C&D
Exhibit	10:00 am – 1:00 pm	Presidential Ballroom, Second Level, Salons A&B
Break	10:10 am – 10:40 am	Presidential Ballroom, Second Level, Salons A&B
WE2: Advanced Technologies and Processes	10:40 am – 12:10 pm	Presidential Ballroom, Second Level, Salons C&D
Lunch	12:10 pm – 2:00 pm	Bivouac Ballroom, Historic Lower Level
Conference Excursions	2:00 pm – 6:00 pm	Off-Site
Conference Dinner Banquet	7:30 pm – 10:00 pm	Bivouac Ballroom, Historic Lower Level

THURSDAY

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EVENT	TIMES	LOCATION
Registration	8:00 am – 5:30 pm	Presidential Foyer, Second Level
TH1: Annealing Technologies and Processes II	9:00 am – 10:10 am	Presidential Ballroom, Second Level, Salons C&D
Exhibit	10:00 am – 12:00 pm	Presidential Ballroom, Second Level, Salons A&B
PS2: Poster Session II	10:10 am – 11:30 am	Presidential Ballroom, Second Level, Salon A&B & Foyer
TH2: Advanced Metrologies for Implant/Doping and Annealing Processes II	11:30 am – 12:40 pm	Presidential Ballroom, Second Level, Salons C&D
Lunch	12:40 pm – 2:00 pm	Bivouac Ballroom, Historic Lower Level
TH3: Implant/Doping Technologies and Processes	2:00 pm – 3:10 pm	Presidential Ballroom, Second Level, Salons C&D
Break	3:10 pm – 3:40 pm	Presidential Ballroom, Second Level, Salons A&B
TH4: Advanced Materials Processing & Closing Remarks	3:40 pm – 5:25 pm	Presidential Ballroom, Second Level, Salons C&D

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